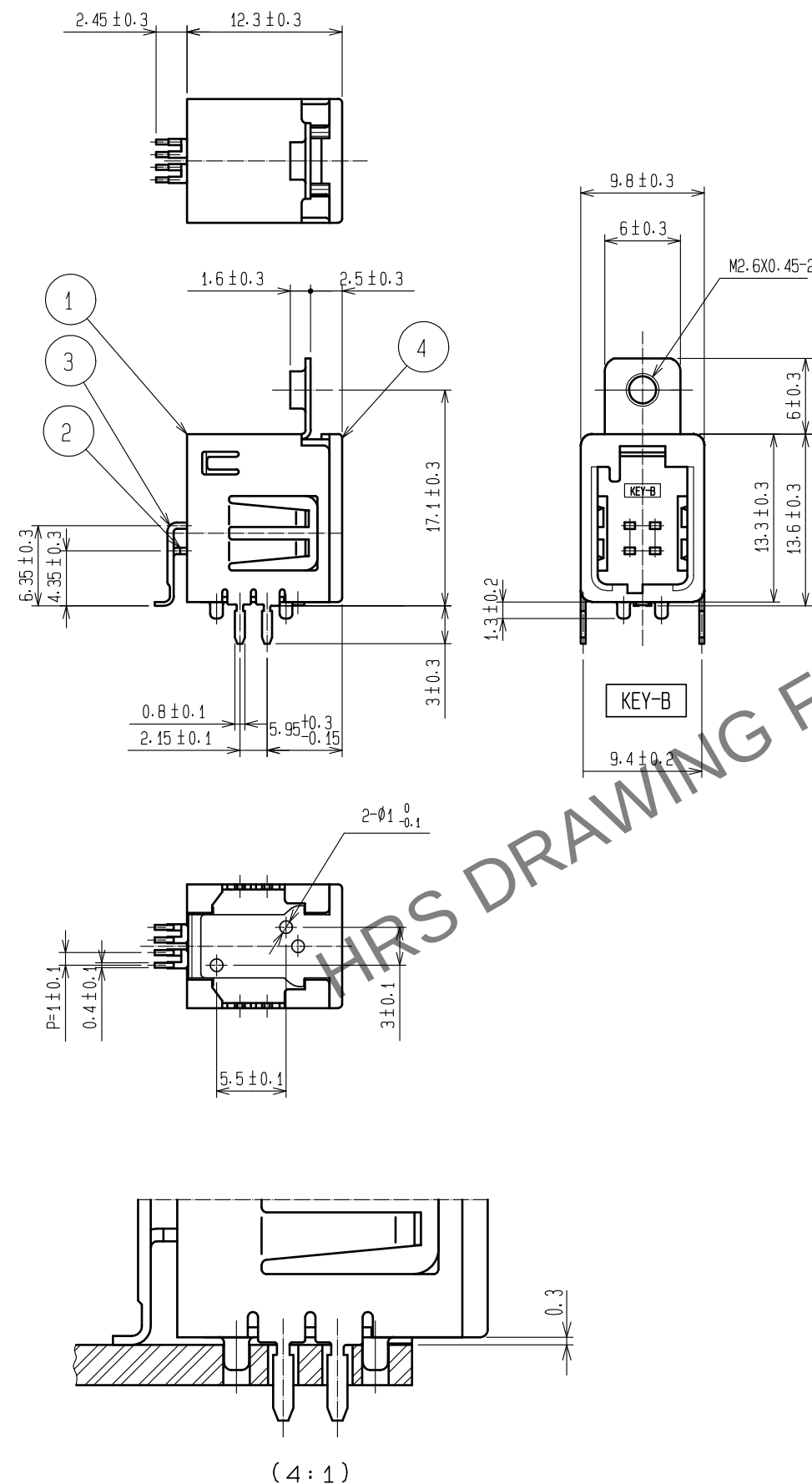
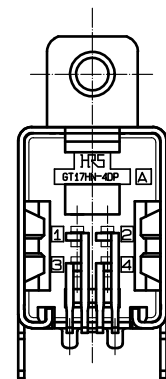


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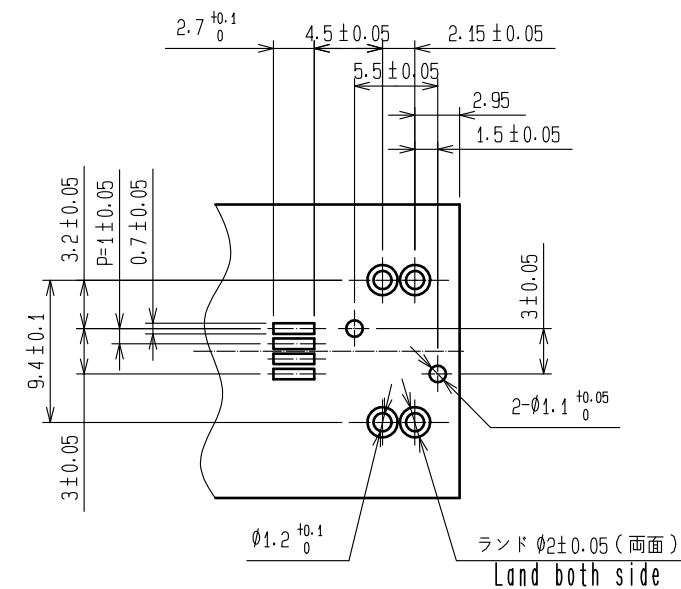
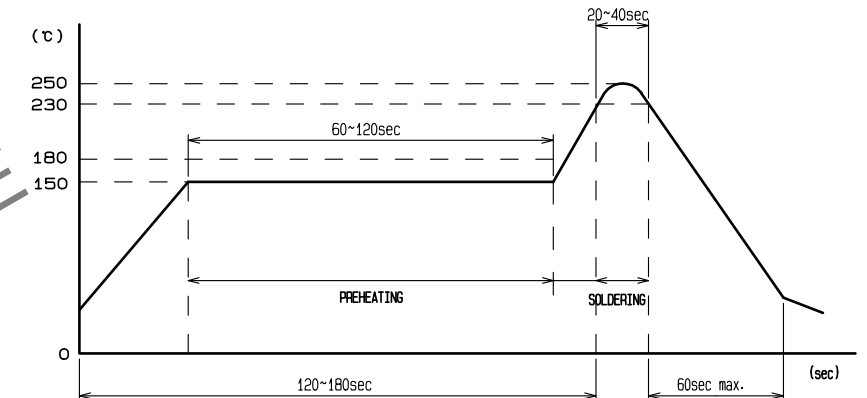
RoHS, ELV適合品

RoHS, ELV COMPLIANT

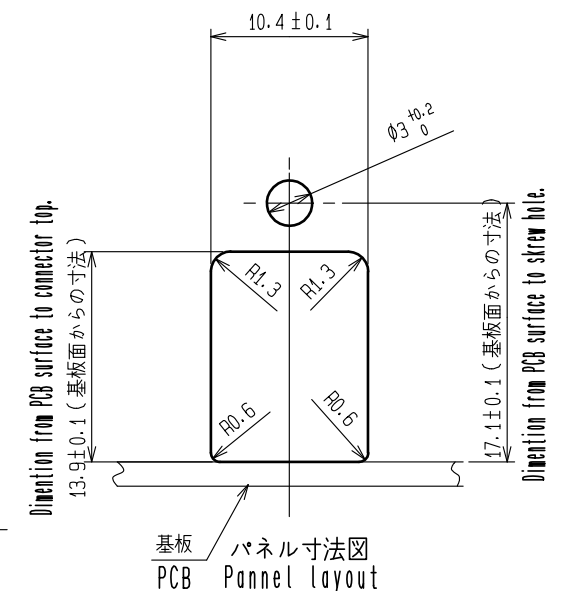


- Note1. The soldering process is allowed up to twice under the same condition. However, the interval between the first and second process must be maintained at the room temperature.
1. リフロー回数: 2回. 但し, 2回目のリフローにおいては, 一度, 室温に戻すこと.
- Note2. The temperature indicates the board surface temperature on the connector lead area.
2. リフロー温度の測定は, コネクタリード部の基板表面温度を測定のこと.
- Note3. Hand soldering: 280~300℃, 2s max.
3. 手半田温度: 280~300℃, 2S以内
- Note4. Coplanarity: 0.1 max.
4. 端子平坦度: 0.1以下
- Note5. Recommended thickness of PCB: 1.6mm.
5. 推奨基板厚: 1.6mm

RECOMMENDED REFLOW PROFILE	
IR reflow condition	IR リフロー条件
Preheating area 150℃ for 60 to 120 seconds	予備加熱: 60~120秒, 150℃
Peak temperature: 250℃	ピーク温度: 250℃
Soldering area 235±5℃ for 10 seconds max.	リフロー温度: 230~240℃, 10秒以内
230℃ min. for 20~40 seconds	230℃以上: 20~40秒



基板推奨寸法図
Recommended PCB layout



基板
PCB
パネル寸法図
Pannel layout

2	BRASS	TIN PLATING	5	PS	TRAY NATURAL
1	COPPER ALLOY	TIN PLATING	4	PPS	GREEN
NO.	MATERIAL	FINISH . REMARKS	3	BRASS	TIN PLATING
UNITS mm		SCALE 2 : 1	NO.	MATERIAL	FINISH . REMARKS
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : KI. HIROKAWA	20200326	DRAWING NO.	EDC-167010-55-00		
CHECKED : EJ. WAKATSUKI	20200325	PART NO.	GT17HN-4DP-2H(B)(55)		
DESIGNED : TS. KUBOTA	20200325	CODE NO.	CL767-0175-0-55		
DRAWN : YK. MITSUISHI	20200221				

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